

# GMM

**Stone Shih**, President

Place: Hyatt

November 23<sup>th</sup>, 2021

- 2021 Q3 Operating Result
- Market Trend & Product Development



# GMM

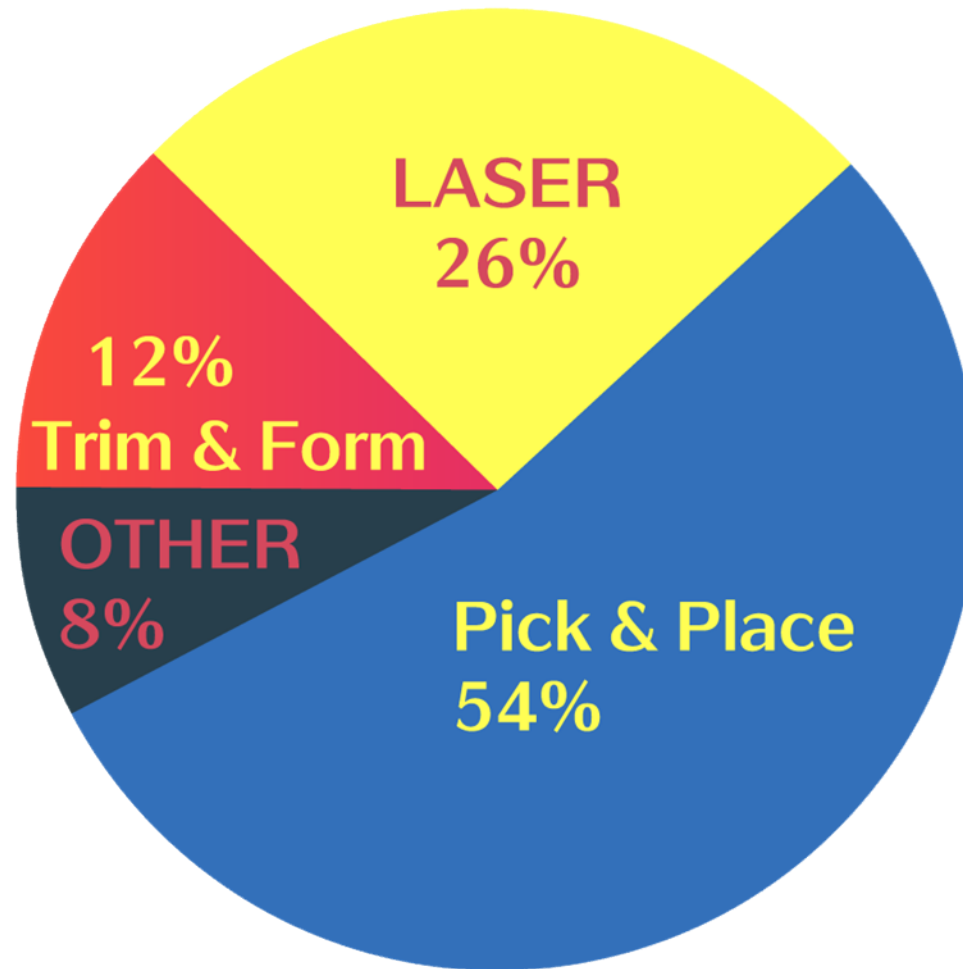
2021 Q3  
Operating Results

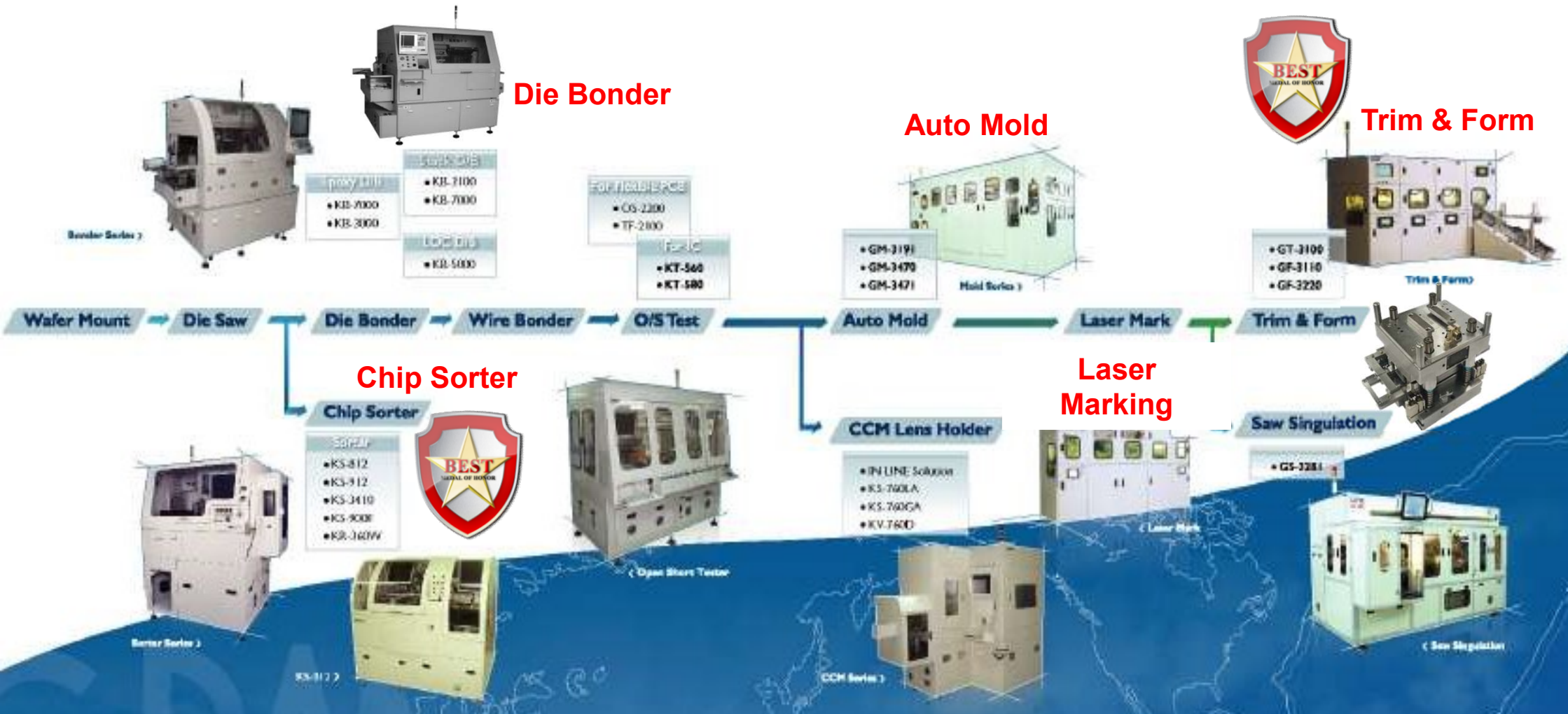
Unit : TWD thousand  
in TWD 千元

Year	2021Q3累計		2020		2019		2018	
Accumulated	Amount	%	Amount	%	Amount	%	Amount	%
Revenue-Consolidated	1,091,464		877,331		758,006		922,261	
COGS	713,432	65.4%	616,404	70.3%	477,057	62.9%	607,763	65.9%
Gross Margin	378,032	34.6%	260,927	29.7%	280,949	37.1%	314,498	34.1%
Net Income before tax	161,680	14.8%	58,453	6.7%	106,877	14.1%	122,094	13.2%
Net Income after tax	128,272	11.8%	44,522	5.1%	85,429	11.3%	87,486	9.5%

ROE	14.10%	4.76%	9.32%	10.20%
EPS (NT\$/after tax)	\$4.75	\$1.57	\$3.02	\$3.33

YOY accumulated revenue growth rate for Q3 2021 is 73%.







## IC Packaging Equipment Industry

ASE GROUP  
日月光集團CHIPBOND  
順邦科技Unimicron  
欣興電子

AI



Cloud Computing



High Performance Computing



Mobile Device



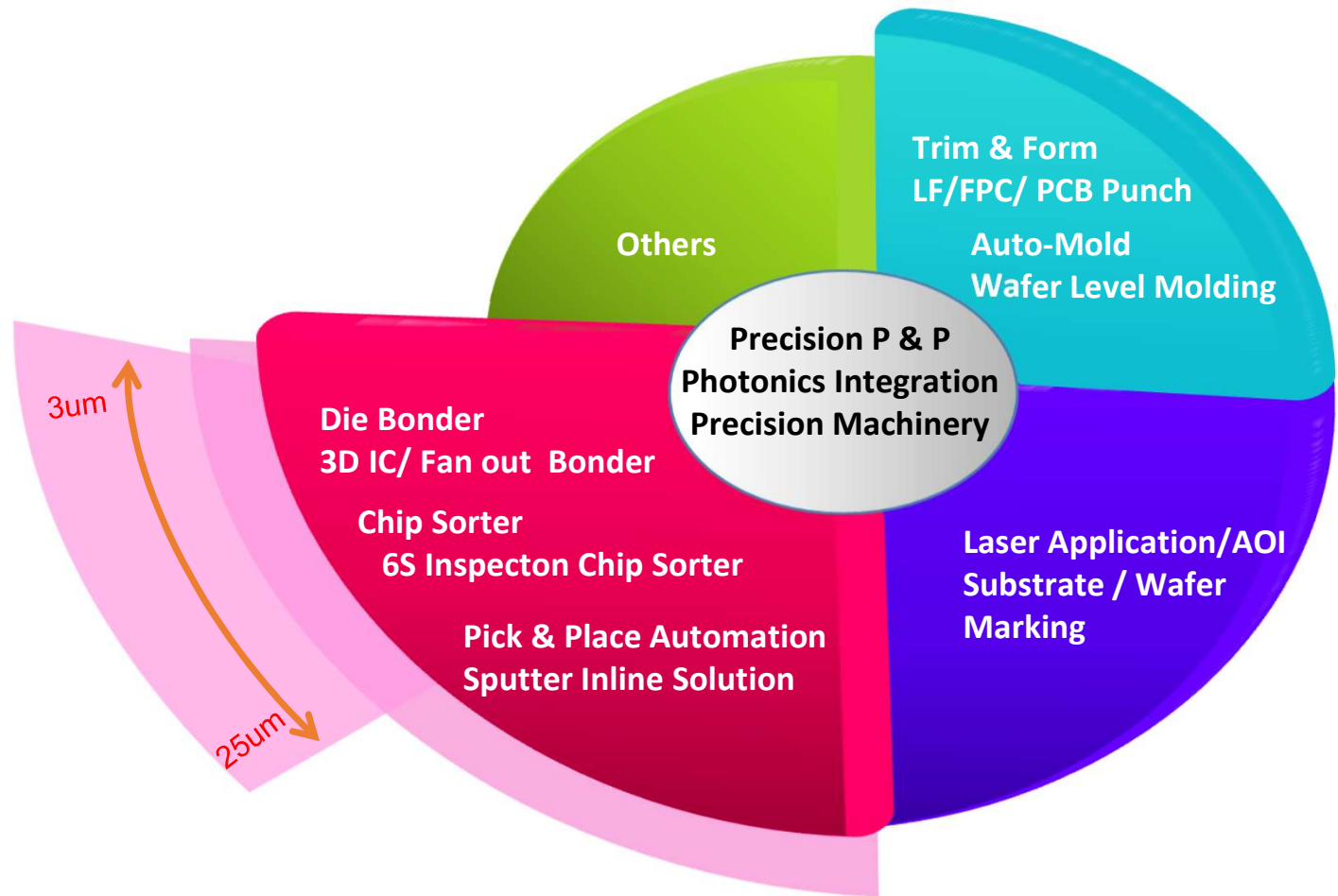
Automotive Electronics



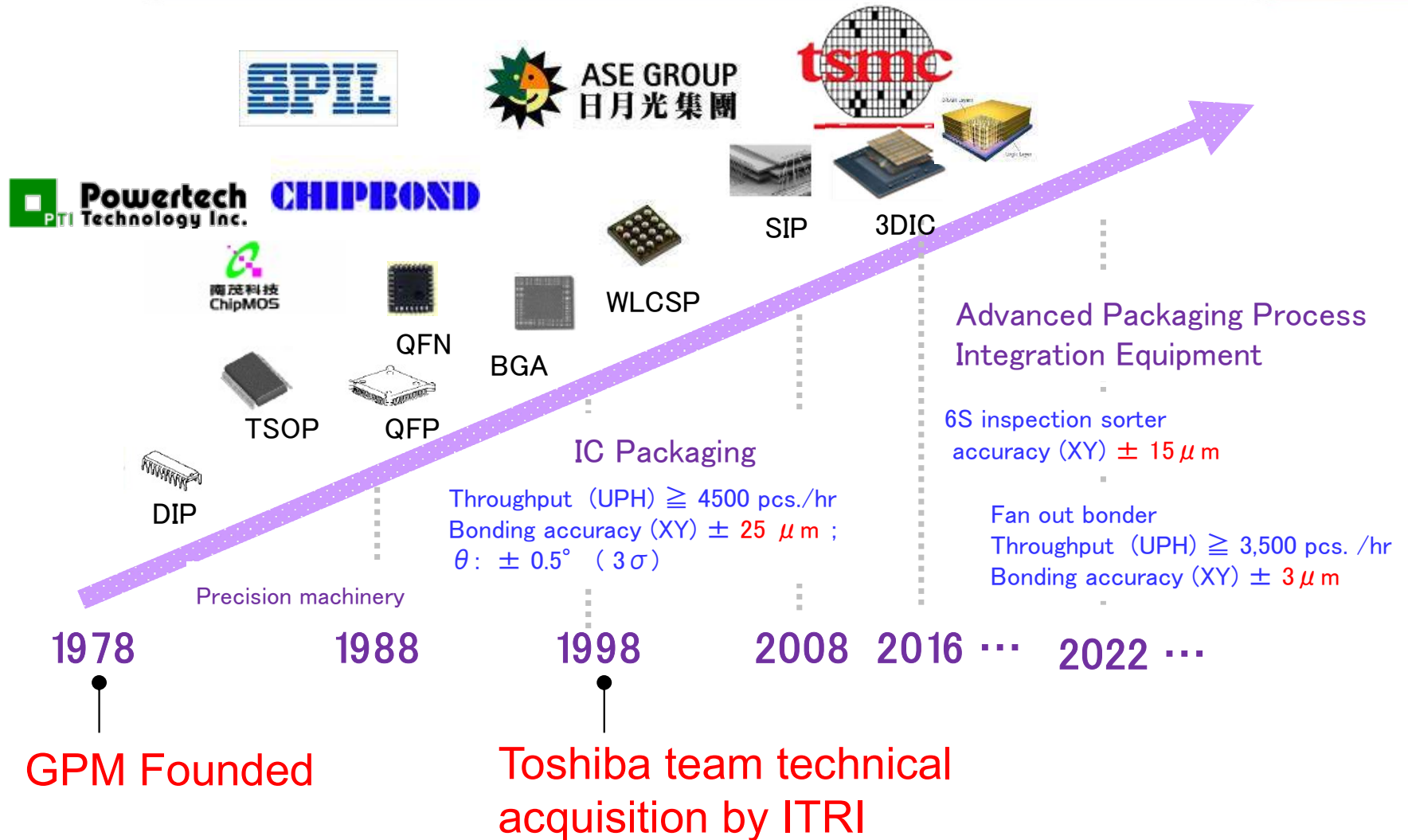
Internet of Things

IC Market  
Advanced Packaging

- Key & Core Technology includes Precision P&P, Photonics integration and precision machinery.
- Market share for Die Pick and Place machine holds over 70% in Taiwan market.
- Market share for Trim and Form machine holds over 40% in Taiwan and China market.
- Laser Marking machine is widely applied in domestic packaging industry.







Storied  
Brand

- Well-recognized by well-known brands in semiconductor industry

Local  
Service

- Fast & efficient solution
- Know market pulse well

Tech  
Develop

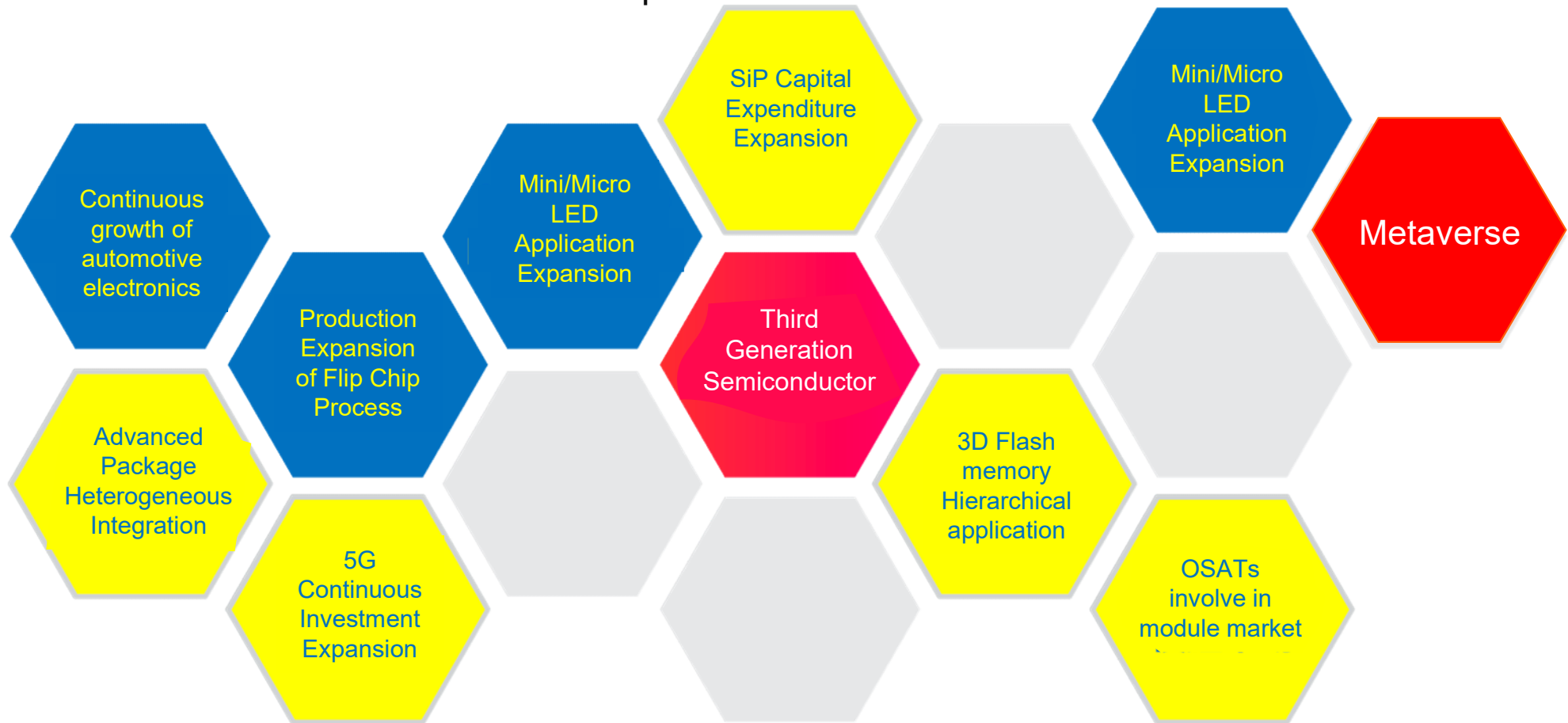
- Mutual development
- New package process equipment

ASE - Best  
Supplier AwardSmart Machine  
Gold Award

- Being a global-class/regional-leading corporate
- Concentrate on specific area and market
- Value-added oriented



Hold the investment trend of 5G/SiP/Flash memory/advance packaging and cultivate core products with innovation





**GMM**

Market Trend & Product  
Development



Precision  
Machining

Trim&Form  
Auto-Mold

Pick and  
Place

Chip Sorter  
Die Bonder

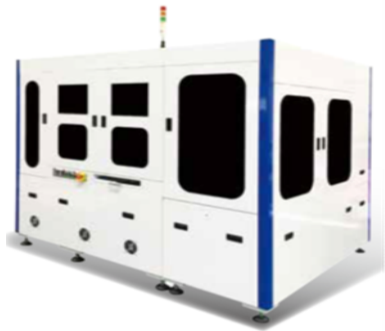
Laser and  
Inspection  
Integration

Laser Mark  
AOI

1. Collaborate with first well-known international brands and provide main process equipment solution.
2. Expand the application of core pick and place precision technology.
3. Continuous get ahead to China market with major products from Taiwan.
4. Raise product value by integrating Laser, AOI and AI technology.
5. Break into tester market with precision control technology.
6. Expand to PCB and panel market application with resource integration of G2C alliance.

# Utron Tester – CCD Auto-Alignment Tester

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U800  
FPC/HDI/CCT

Single-arm Auto Tester



U820  
IC Substrate/  
Rigid-flex board

Dual-arm Auto Tester



U20ST/EX  
HDI

Turntable Tester



8192 (I/O: 4096)  
2+4W Test System

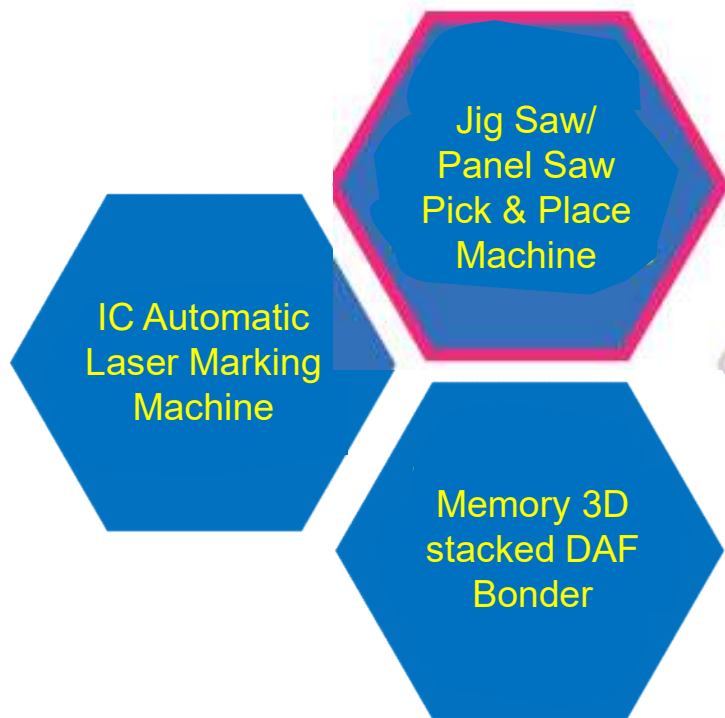
Under  
verification  
by first well-  
known  
customer

Market Scale : 200 sets/year. over US\$ 100 million

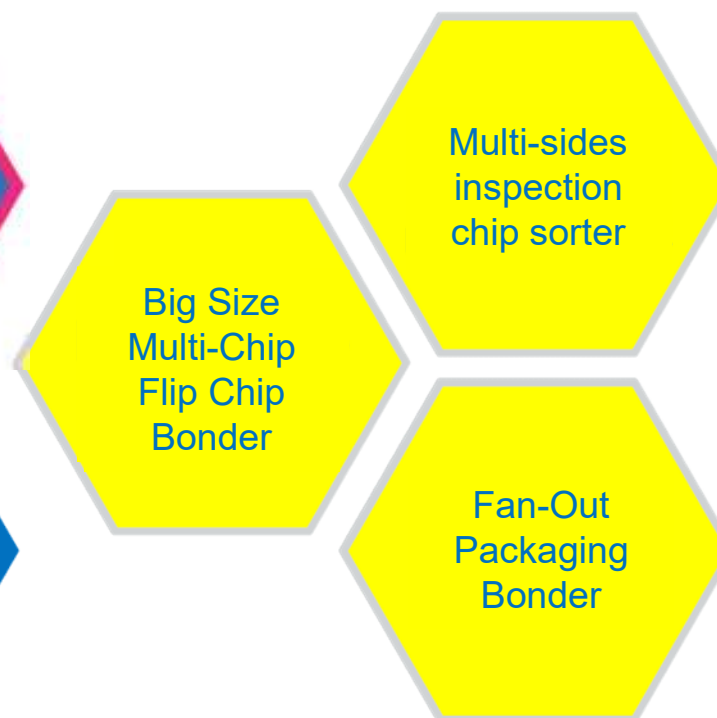
Applied on IC substrate / HDI / Automobile / 5G and all IC relevant PCB tester.

Pay tribute to Japan R company

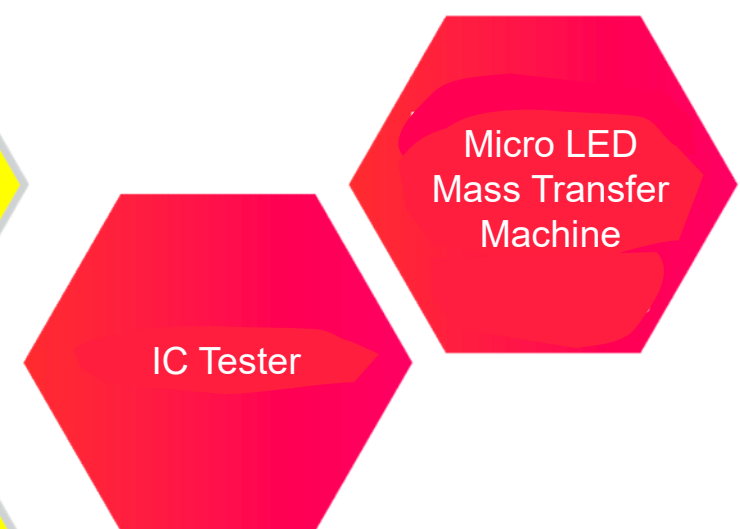
## High-End Performance Packaging



## Advanced Packaging



## Enlarge the applying scope









# G2C+

係由夥伴公司共組之團隊聯盟

## Q & A



11/23<sup>(=)</sup>  
2021

**G2C+**

**Thank You**  
**聯盟法人說明會**

Alliance Conference Call